

4. Absolute Maximum Ratings (Note) (Ta = 25 °C unless otherwise specified)

Characteristic	cs		Symbol	Rating	Unit
Drain-source voltage			V_{DSS}	30	V
Gate-source voltage			V _{GSS}	±20	
Drain current (DC)	(Silicon limit)	(Note 1), (Note 2)	I _D	220	Α
Drain current (DC)	(T _c = 25 °C)	(Note 1)	I _D	60	
Drain current (pulsed)	(t = 1 ms)	(Note 1)	I _{DP}	200	
Power dissipation	(T _c = 25 °C)		P_{D}	78	W
Power dissipation	(t = 10 s)	(Note 3)	P_{D}	2.8	
Power dissipation	(t = 10 s)	(Note 4)	P_{D}	1.6	
Single-pulse avalanche energy		(Note 5)	E _{AS}	889	mJ
Avalanche current			I _{AR}	60	Α
Channel temperature			T _{ch}	150	ů
Storage temperature			T _{stg}	-55 to 150	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

5. Thermal Characteristics

Characteristics			Symbol	Max	Unit
Channel-to-case thermal resistance	(T _c = 25 °C)		R _{th(ch-c)}	1.60	°C/W
Channel-to-ambient thermal resistance	(t = 10 s)	(Note 3)	R _{th(ch-a)}	44.6	
Channel-to-ambient thermal resistance	(t = 10 s)	(Note 4)	R _{th(ch-a)}	78.1	

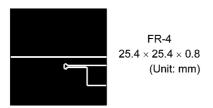
Note 1: Ensure that the channel temperature does not exceed 150 °C.

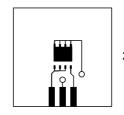
Note 2: Limited by silicon chip capability.

Note 3: Device mounted on a glass-epoxy board (a), Figure 5.1

Note 4: Device mounted on a glass-epoxy board (b), Figure 5.2

Note 5: V_{DD} = 24 V, T_{ch} = 25 °C (initial), L = 0.19 mH, I_{AR} = 60 A





 $\begin{aligned} & \text{FR-4} \\ 25.4 \times 25.4 \times 0.8 \\ & \text{(Unit: mm)} \end{aligned}$

Fig. 5.1 Device Mounted on a Glass-Epoxy Board (a)

Fig. 5.2 Device Mounted on a Glass-Epoxy Board (b)

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.



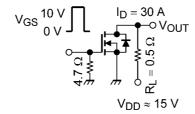
6. Electrical Characteristics

6.1. Static Characteristics ($T_a = 25$ °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current	I _{GSS}	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±0.1	μΑ
Drain cut-off current	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V	_	_	10	
Drain-source breakdown voltage	V _{(BR)DSS}	I _D = 10 mA, V _{GS} = 0 V	30	_		٧
	V _{(BR)DSX}	$I_D = 10 \text{ mA}, V_{GS} = -20 \text{ V}$	15	_	_	
Gate threshold voltage	V_{th}	V _{DS} = 10 V, I _D = 1.0 mA	1.3	_	2.3	
Drain-source on-resistance	R _{DS(ON)}	$V_{GS} = 4.5 \text{ V}, I_D = 30 \text{ A}$	_	1.1	1.4	mΩ
		V_{GS} = 10 V, I_{D} = 30 A	_	0.77	0.9	

6.2. Dynamic Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C _{iss}	V _{DS} = 15 V, V _{GS} = 0 V, f = 1 MHz	_	5300	6900	pF
Reverse transfer capacitance	C _{rss}		_	130	270	
Output capacitance	C _{oss}		_	2700	_	
Gate resistance	r _g	_	_	1.2	1.8	Ω
Switching time (rise time)	t _r	See Fig. 6.2.1	_	9.6	_	ns
Switching time (turn-on time)	t _{on}		_	23	_	
Switching time (fall time)	t _f		_	15	_	
Switching time (turn-off time)	t _{off}		_	89		



Duty \leq 1%, $t_W=10~\mu s$

Fig. 6.2.1 Switching Time Test Circuit

6.3. Gate Charge Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus	Q_g	$V_{DD} \approx 15 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 60 \text{ A}$	_	74		nC
gate-drain)		$V_{DD} \approx 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 60 \text{ A}$		32		
Gate-source charge 1	Q _{gs1}	$V_{DD} \approx 15 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 60 \text{ A}$	_	19		
Gate-drain charge	Q_{gd}		_	6.5		
Gate switch charge	Q_{SW}		_	16	_	

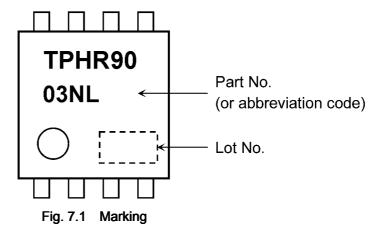
6.4. Source-Drain Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Reverse drain current (pulsed)	(Note 6)	I _{DRP}	_	_	_	200	Α
Diode forward voltage		V _{DSF}	I _{DR} = 60 A, V _{GS} = 0 V	_		-1.2	V

Note 6: Ensure that the channel temperature does not exceed 150 °C.



7. Marking





8. Characteristics Curves (Note)

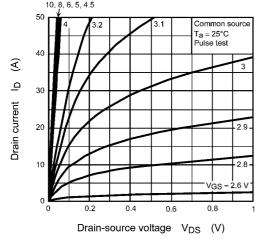
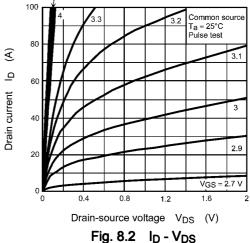


Fig. 8.1 I_D - V_{DS}



10, 8, 6, 5, 4.5

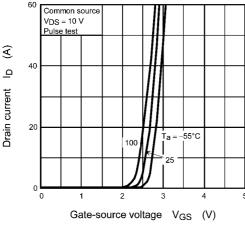


Fig. 8.3 ID - VGS

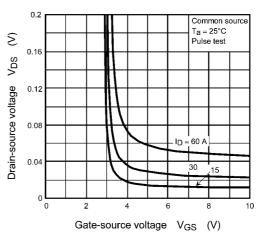


Fig. 8.4 VDS - VGS

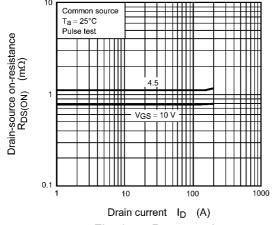


Fig. 8.5 R_{DS(ON)} - I_D

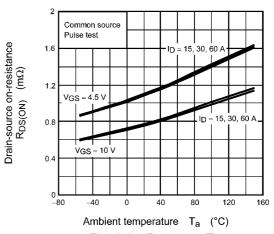


Fig. 8.6 R_{DS(ON)} - T_a



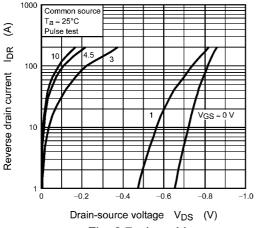
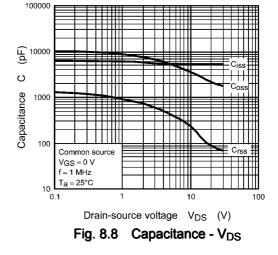


Fig. 8.7 I_{DR} - V_{DS}



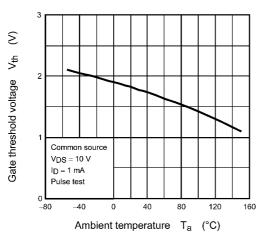


Fig. 8.9 V_{th} - T_a

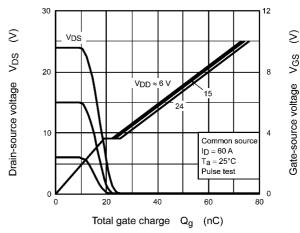


Fig. 8.10 Dynamic Input/Output Characteristics

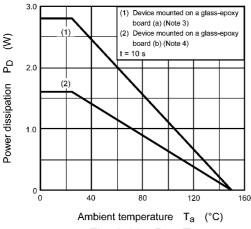


Fig. 8.11 P_D - T_a (Guaranteed Maximum)

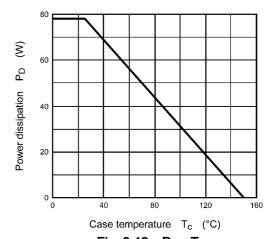


Fig. 8.12 P_D - T_c (Guaranteed Maximum)

Downloaded from Arrow.com.



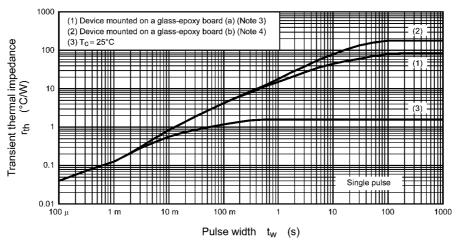


Fig. 8.13 r_{th} - t_w (Guaranteed Maximum)

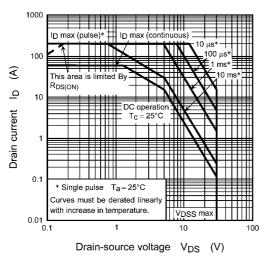


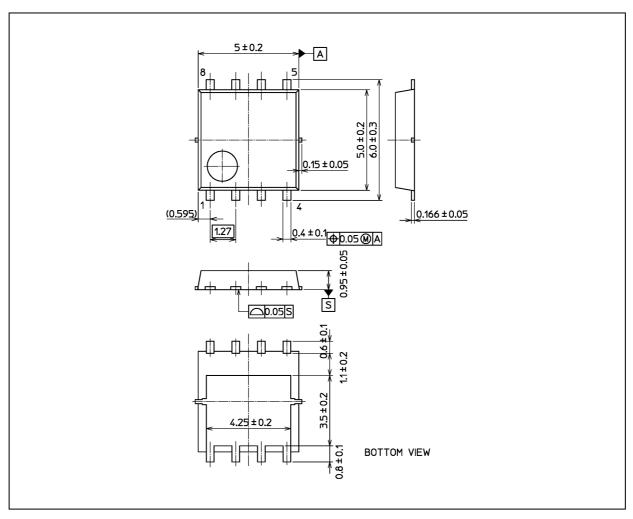
Fig. 8.14 Safe Operating Area (Guaranteed Maximum)

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



Package Dimensions

Unit: mm



The package can be selected according to your preference. For details, please contact your TOSHIBA sales representative.

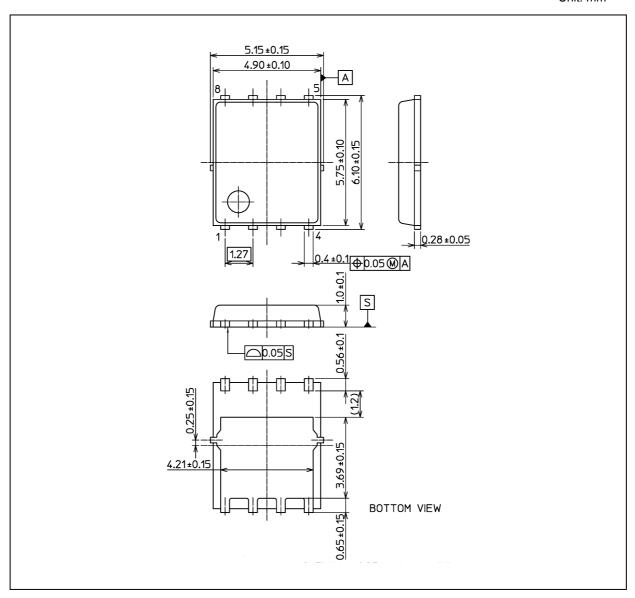
Weight: 0.087 g (typ.)

i	Package Name(s)
TOSHIBA: 2-5Q1S	
Nickname: SOP Advance	



Package Dimensions

Unit: mm



The package can be selected according to your preference. For details, please contact your TOSHIBA sales representative.

Weight: 0.111 g (typ.)

Package Name(s)
TOSHIBA: 2-5W1A
Nickname: SOP Advance(N)



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